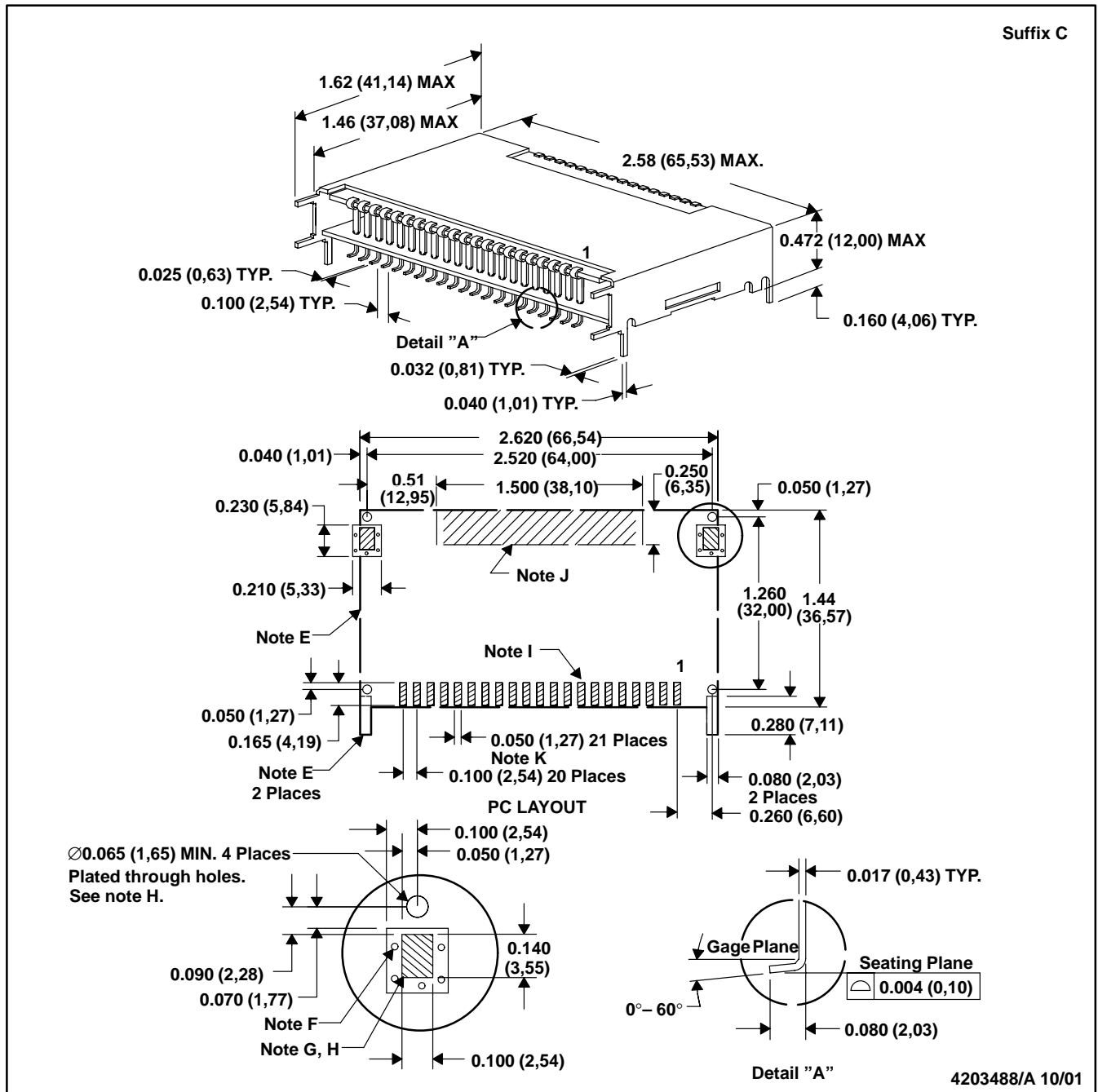


ENP (R-MSIP-G21)

METAL SINGLE-IN-LINE MODULE

Suffix C



- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - E. Recommended mechanical keep out area.
 - F. Vias are recommended to improve copper adhesion.
 - G. Solder mask openings to copper island for solder joints to mechanical pins.
 - H. The case is electrically uncommitted. The recommended connection is to secondary ground.
 - I. Power pin connections should utilize two or more vias per input, ground and output pin.
 - J. No copper, power or signal traces in this area.
 - K. Some pins may not be present, see product specifications.

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